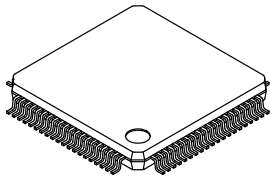
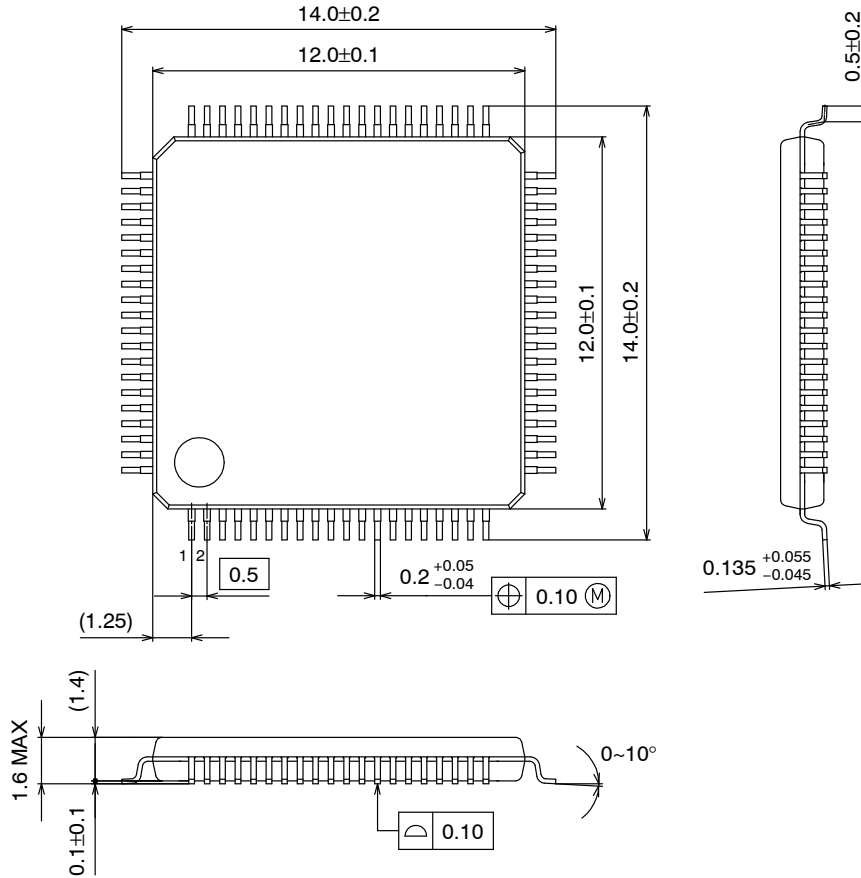


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

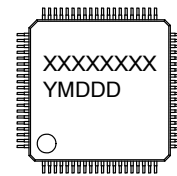
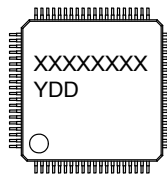


SPQFP80 12x12 / SQFP80
CASE 131AL
ISSUE A

DATE 25 NOV 2013



GENERIC MARKING DIAGRAM*



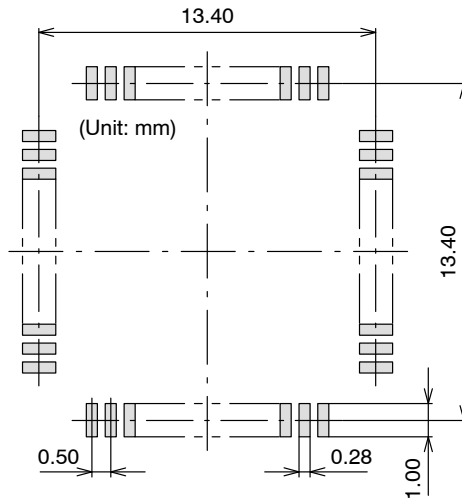
XXXXX = Specific Device Code
 Y = Year
 DD = Additional Traceability Data

XXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

DOCUMENT NUMBER:	98AON79380E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPQFP80 12X12 / SQFP80	PAGE 1 OF 3

SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON79380E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPQFP80 12X12 / SQFP80	PAGE 2 OF 3

